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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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# BLC10G18XS-550AVT

# Power LDMOS transistor Rev. 1 — 21 December 2017

**AMMPLEON** 

Product data sheet

#### **Product profile** 1.

#### 1.1 General description

550 W LDMOS packaged asymmetric Doherty power transistor for base station applications at frequencies from 1805 MHz to 1880 MHz.

#### Typical performance

Typical RF performance at  $T_{case} = 25$  °C in an asymmetrical Doherty production test circuit.  $V_{DS}$  = 28 V;  $I_{Dq}$  = 800 mA (main);  $V_{GS(amp)peak}$  = 0.95 V, unless otherwise specified.

Test signal	f	V <sub>DS</sub>	P <sub>L(AV)</sub>	G <sub>p</sub>	η <sub>D</sub>	ACPR
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
1-carrier W-CDMA	1805 to 1880	28	91	16.5	49.3	-29.4 <sup>[1]</sup>

<sup>[1]</sup> Test signal: 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.9 dB at 0.01 % probability on

#### 1.2 Features and benefits

- Excellent ruggedness
- High efficiency
- Low thermal resistance providing excellent thermal stability
- Lower output capacitance for improved performance in Doherty applications
- Designed for low memory effects providing excellent digital pre-distortion capability
- Internally matched for ease of use
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

#### 1.3 Applications

RF power amplifiers for base stations and multi carrier applications in the 1805 MHz to 1880 MHz frequency range

### 2. Pinning information

Table 2. Pinning

Pin	Description		Simplified outline	Graphic symbol
1	drain2 (peak)			0.7
2	drain1 (main)		7 2 1 6	2, 7
3	gate1 (main)		5	<u> </u>
4	gate2 (peak)		3 4	3——5
5	source	[1]		4—
6	video decoupling (peak)			" <del>'</del> ¬
7	video decoupling (main)			1, 6 aaa-014884

<sup>[1]</sup> Connected to flange.

### 3. Ordering information

Table 3. Ordering information

Type number	Packag	ackage				
	Name	Name Description Version				
BLC10G18XS-550AVT	-	air cavity plastic earless flanged package; 6 leads	SOT1258-4			

### 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	65	V
V <sub>GS(amp)main</sub>	main amplifier gate-source voltage		-6	+9	V
V <sub>GS(amp)peak</sub>	peak amplifier gate-source voltage		-6	+9	V
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature	[1]	-	225	°C
T <sub>case</sub>	case temperature	operating [1]	-40	+125	°C

<sup>[1]</sup> Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

#### 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R <sub>th(j-c)</sub>	thermal resistance from junction	$V_{DS}$ = 32 V; $I_{Dq}$ = 800 mA (main);		
	to case	V <sub>GS(amp)peak</sub> = 1.1 V; T <sub>case</sub> = 80 °C		
		P <sub>L</sub> = 110 W	0.187	k/W
		P <sub>L</sub> = 138 W	0.166	k/W

BLC10G18XS-550AVT

#### 6. Characteristics

Table 6. DC characteristics

 $T_i$  = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit					
Main dev	Main device										
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 1.8 \text{ mA}$	65	-	-	V					
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 180 mA	1.5	2.0	2.5	V					
$V_{GSq}$	gate-source quiescent voltage	V <sub>DS</sub> = 28 V; I <sub>D</sub> = 800 mA	-	2.2	-	V					
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 32 V	-	-	2.8	μА					
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 2.37 \text{ V}$	-	34	-	Α					
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 9 V; V <sub>DS</sub> = 0 V	-	-	280	nA					
9 <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 9.0 A	-	20.5	-	S					
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 2.37 \text{ V};$ $I_D = 6.3 \text{ A}$	-	72	108	mΩ					
Peak dev	rice		•								
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 3.8 \text{ mA}$	65	-	-	V					
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 380 mA	1.5	2.0	2.5	V					
$V_{GSq}$	gate-source quiescent voltage	V <sub>DS</sub> = 28 V; I <sub>D</sub> = 2000 mA	-	2.2	-	V					
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 32 V	-	-	2.8	μА					
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 2.37 \text{ V}$	-	57	-	Α					
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 9 V; V <sub>DS</sub> = 0 V	-	-	280	nA					
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 19.0 A	-	39.0	-	S					
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 2.37 \text{ V};$ $I_D = 13.3 \text{ A}$	-	37	62	mΩ					

#### Table 7. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1 to 64 DPCH;  $f_1$  = 1807.5 MHz;  $f_2$  = 1877.5 MHz; RF performance at  $V_{DS}$  = 28 V;  $I_{Dq}$  = 800 mA (main);  $V_{GS(amp)peak}$  = 1.0 V;  $T_{case}$  = 25 °C; unless otherwise specified; in an asymmetrical Doherty production test circuit at frequencies from 1805 MHz to 1880 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Gp	power gain	P <sub>L(AV)</sub> = 93 W	15.0	16.0	-	dB
RLin	input return loss	P <sub>L(AV)</sub> = 93 W	-	-19	-13	dB
$\eta_{D}$	drain efficiency	P <sub>L(AV)</sub> = 93 W	45	50	-	%
ACPR	adjacent channel power ratio	P <sub>L(AV)</sub> = 93 W	-	-26	-22	dBc

#### Table 8. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1 to 64 DPCH; f = 1807.5 MHz; RF performance at  $V_{DS}$  = 28 V;  $I_{Dq}$  = 800 mA (main);  $V_{GS(amp)peak}$  = 1.0 V;  $T_{case}$  = 25 °C; unless otherwise specified; in an asymmetrical Doherty production test circuit at a frequency of 1805 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
PARO	output peak-to-average ratio	P <sub>L(AV)</sub> = 118 W	5.8	6.3	-	dB
$P_{L(M)}$	peak output power	P <sub>L(AV)</sub> = 118 W	440	510	-	W

### 7. Test information

#### 7.1 Ruggedness in Doherty operation

The BLC10G18XS-550AVT is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA;  $V_{GS(amp)peak}$  = 1.05 V; f = 1807.5 MHz;  $P_L$  = 213 W (5 dB OBO); 46 % clipping.

### 7.2 Impedance information

Table 9. Typical impedance of main device Measured load-pull data of main device;  $I_{Dq}$  = 1000 mA (main);  $V_{DS}$  = 28 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)
Maximun	n power load				
1805	1.4 – 4.9i	1.8 – 3.1i	269	62.8	17.6
1845	1.6 – 5.2i	1.8 – 3.1i	266	63.2	18.0
1880	2.1 – 5.6i	1.7 – 3.2i	265	60.7	18.0
Maximun	n drain efficiency	load			
1805	1.4 – 4.9i	3.1 – 2.3i	213	69.6	19.4
1845	1.6 – 5.2i	2.8 – 2.3i	216	69.3	19.6
1880	2.1 – 5.6i	2.5 – 2.1i	211	69.2	19.7

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

<sup>[2]</sup> At 3 dB gain compression.

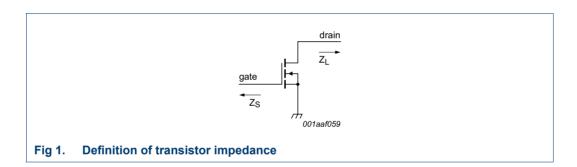
Table 10. Typical impedance of peak device

Measured load-pull data of peak device;  $I_{Dq}$  = 2100 mA (peak);  $V_{DS}$  = 28 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]					
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)					
Maximum	Maximum power load									
1805	1.7 – 5.6i	1.0 – 3.3i	488	57.6	15.8					
1845	2.0 – 6.0i	1.0 – 3.4i	481	56.3	16.0					
1880	2.6 – 6.5i	1.1 – 3.5i	475	56.0	16.2					
Maximum	drain efficiency	load								
1805	1.7 – 5.6i	1.7 – 2.6i	378	66.0	17.7					
1845	2.0 – 6.0i	1.5 – 2.4i	343	65.4	18.2					
1880	2.6 – 6.5i	1.5 – 2.5i	356	65.1	18.2					

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

<sup>[2]</sup> At 3 dB gain compression.



### 7.3 Recommended impedances for Doherty design

#### Table 11. Typical impedance of main at 1:1 load

Measured load-pull data of main device;  $I_{Dq}$  = 1000 mA (main);  $V_{DS}$  = 28 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L(3dB)</sub> [2]	η <b>D</b> [2]	G <sub>p</sub> [2]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)
1805	1.7 – j5.0	1.8 – j3.6	244	39.9	20.0
1845	2.1 – j5.3	1.7 – j3.3	247	40.5	20.4
1880	2.5 – j5.7	1.7 – j3.0	247	41.7	20.8

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

<sup>[2]</sup> At  $P_{L(AV)} = 115 \text{ W}$ .

Table 12. Typical impedance of main device at 1: 2.5 load

Measured load-pull data of main device;  $I_{Dq}$  = 1000 mA (main);  $V_{DS}$  = 28 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L(3dB)</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)
1805	1.7 – j5.0	3.9 – j1.3	144	55.5	22.9
1845	2.1 – j5.3	3.8 – j1.1	134	56.5	23.5
1880	2.5 – j5.7	3.8 – j0.8	124	56.4	23.9

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

#### Table 13. Typical impedance of peak device at 1:1 load

Measured load-pull data of peak device;  $I_{Dq}$  = 2100 mA (peak);  $V_{DS}$  = 28 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L(3dB)</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)
1805	1.6 – j5.1	1.7 – j3.9	397	31.5	18.7
1845	2.0 – j5.5	1.6 – j3.7	416	31.2	19.0
1880	3.0 – j6.4	1.5 – j3.5	422	31.5	19.4

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

Table 14. Off-state impedances of peak device

f	Z <sub>off</sub>
(MHz)	$(\Omega)$
1805	1.0 – j1.2
1845	0.7 – j0.4
1880	0.5 + j0.2

<sup>[2]</sup> At  $P_{L(AV)} = 115 \text{ W}$ .

<sup>[2]</sup> At  $P_{L(AV)} = 115 W$ .

#### 7.4 Test circuit

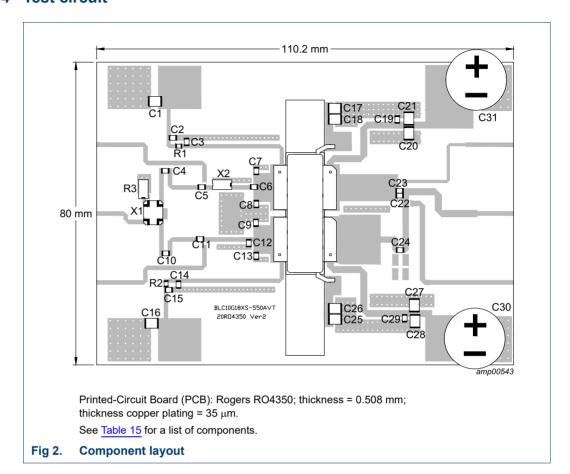
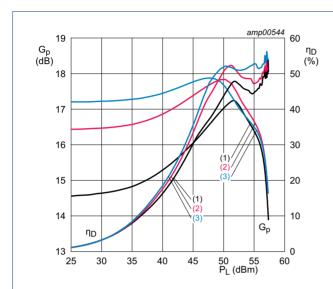


Table 15. List of components

See Figure 2 for component layout. **Description Value** Remarks Component C1, C16, C17, C18, C20, multilayer ceramic chip capacitor 4.7 μF, 50 V SMD 1210. Murata: C21, C25, C26, C27, C28 GRM32ER71H475KA88L C2. C15 multilayer ceramic chip capacitor 100 nF, 50 V C3, C4, C5, C6, C10, C11, multilayer ceramic chip capacitor 10 pF

#### 7.5 Graphical data

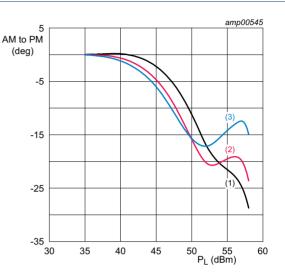
#### 7.5.1 Pulsed CW



 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 1.05 \text{ V}.$ 

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 3. Power gain and drain efficiency as function of output power; typical values



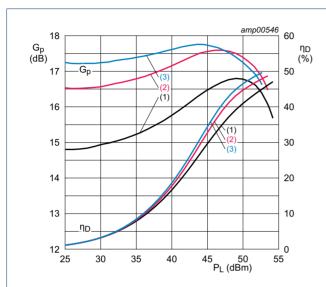
 $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA;  $V_{GS(amp)peak}$  = 1.05 V.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 4. Normalized AM to PM as a function of output power; typical values

#### 7.5.2 1-Carrier W-CDMA

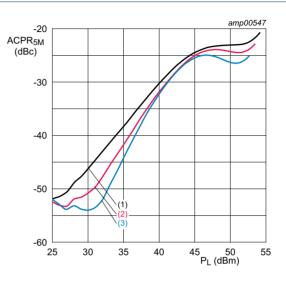
Test signal: 3GPP test model 1; 1 to 64 DPCH (100 % clipping): PAR = 7.5 dB per carrier at 0.01 % probability on CCDF per carrier.



 $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA;  $V_{GS(amp)peak}$  = 1.05 V.

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

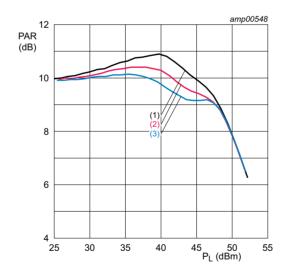
Fig 5. Power gain and drain efficiency as function of output power; typical values



 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 1.05 \text{ V}.$ 

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 6. Adjacent channel power ratio (5 MHz) as a function of output power; typical values



 $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA;  $V_{GS(amp)peak}$  = 1.05 V.

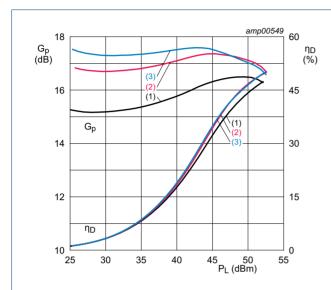
- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 7. Peak-to-average power ratio as a function of output power; typical values

BLC10G18XS-550AVT

#### 7.5.3 2-Carrier W-CDMA

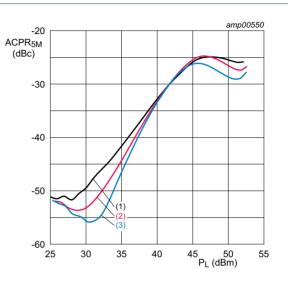
Test signal: 3GPP test model 1; 1 to 64 DPCH (46 % clipping): PAR = 7.5 dB per carrier at 0.01 % probability on CCDF per carrier.



 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 1.05 \text{ V}.$ 

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 8. Power gain and drain efficiency as function of output power; typical values

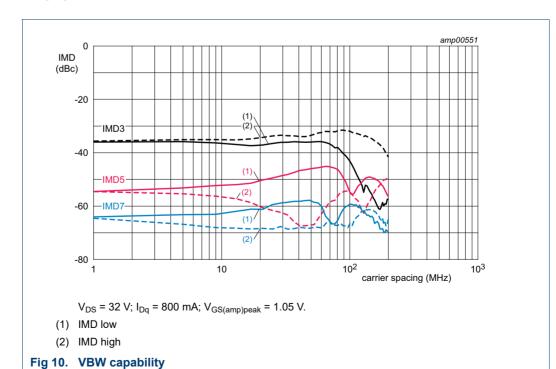


 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 1.05 \text{ V}.$ 

- (1) f = 1805 MHz
- (2) f = 1842.5 MHz
- (3) f = 1880 MHz

Fig 9. Adjacent channel power ratio (5 MHz) as a function of output power; typical values

#### 7.5.4 2-Tone VBW

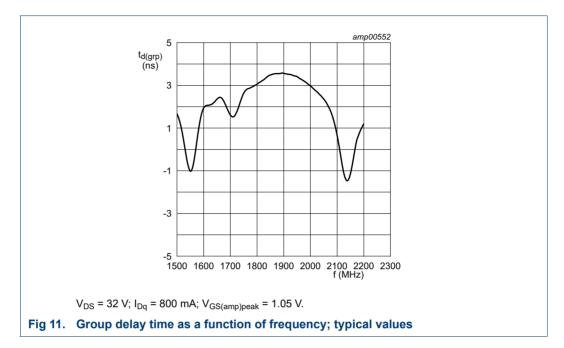


BLC10G18XS-550AVT

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#### 7.5.5 Group delay



### 8. Package outline

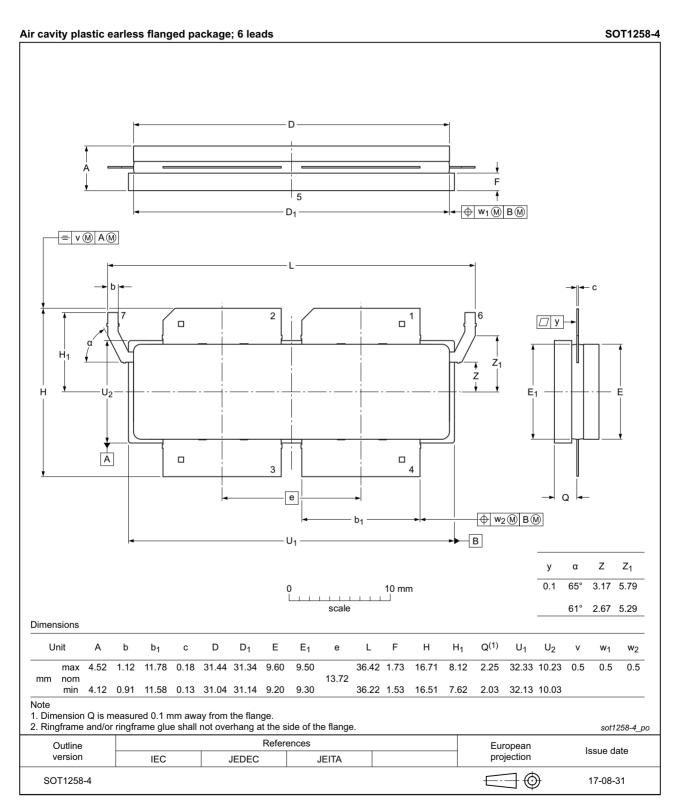


Fig 12. Package outline SOT1258-4

### 9. Handling information

#### **CAUTION**



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 16. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C3 [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

- [1] CDM classification C3 is granted to any part that passes after exposure to an ESD pulse of 1000 V.
- [2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V, but fails after exposure to an ESD pulse of 4000 V.

#### 10. Abbreviations

Table 17. Abbreviations

Acronym	Description
3GPP	3rd Generation Partnership Project
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
MTF	Median Time to Failure
ОВО	Output Back Off
PAR	Peak-to-Average Ratio
SMD	Surface Mounted Device
VBW	Video BandWidth
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

### 11. Revision history

Table 18. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLC10G18XS-550AVT v.1	20171221	Product data sheet	-	-

### 12. Legal information

#### 12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.ampleon.com.

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BLC10G18XS-550AVT

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### **BLC10G18XS-550AVT**

#### **Power LDMOS transistor**

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#### **Power LDMOS transistor**

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